



Features

- 0402 and 0603 package options
- Rated for IEC 61000-4-2, level 4
- Withstands multiple ESD strikes
- Low capacitance and leakage currents for invisible load protection
- Tape and reel packaging

ChipGuard® MLA Series Varistor ESD Clamp Protectors

Description

The ChipGuard® CG0402MLA and CG0603MLA Series are based on a multilayer metal oxide technology. The MLA family is designed to protect sensitive electronic circuits from the threat of electrostatic discharge ESD. The MLA series is available from 5.5 V to 26 V DC working voltages.

The wide operating voltage and temperature range makes this family ideally suited to IC power supplies, signal and control line protection.

Electrical Characteristics @ 25 °C (unless otherwise noted)

Model	Vrms (V)	VDC (V)	VN Min. (V)	VN Max. (V)	VC (V)	ITM (Max.) (A)	WTM (Max.) (J)	CP (pF) Typ.
	<50 μ A		1 mA DC		1 A @ 8/20 μ s	@ 8/20 μ s	10/1000 μ s	@ 1 MHz
CG0402MLA-5.5MG	4	5.5	6.4	9.6	19	20	0.05	270
CG0402MLA-14KG	11	14	16.2	19.8	38	20	0.05	90
CG0402MLA-14LG	11	14	15.3	20.7	30	20	0.05	100
CG0402MLA-18KG	14	18	19.8	24.2	45	20	0.05	85
CG0603MLA-5.5ME	4	5.5	6.4	9.6	19	30	0.1	270
CG0603MLA-14KE	11	14	16.2	19.8	35	30	0.1	150
CG0603MLA-18KE	14	18	19.8	24.2	40	30	0.1	130
CG0603MLA-26KE	20	26	27.9	34.1	58	30	0.1	100

Environmental Characteristics

Operating Temperature.....-55 °C to +125 °C
 Storage Temperature.....-55 °C to +125 °C
 Response Time.....<1 ns
 Standard.....IEC 61000-4-2 Level 4

These products are RoHS compliant. There is some lead contained within the glass of the ceramic. This is acceptable under exemption no. 5 of the RoHS directive (DIRECTIVE 2002/95/EC OF THE EUROPEAN PARLIAMENT AND OF THE COUNCIL of 27 January 2003 on the restriction of the use of certain hazardous substances in electrical and electronic equipment).

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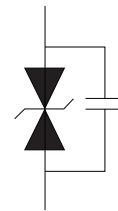
Asia-Pacific: Tel: +886-2 2562-4117 • Fax: +886-2 2562-4116

Europe: Tel: +41-41 768 5555 • Fax: +41-41 768 5510

The Americas: Tel: +1-951 781-5500 • Fax: +1-951 781-5700

www.bourns.com

Device Symbol



How to Order

CG 0n0n MLA - n.n x x

ChipGuard®
 Product Designator

Package Option
 0402 = 0402 Package
 0603 = 0603 Package

Multilayer Series Designator

Operating Voltage**
 5.5 = 5.5 V
 14 = 14 V
 18 = 18 V
 26 = 26 V

Tolerance
 K = 10 %
 L = 15 %
 M = 20 %

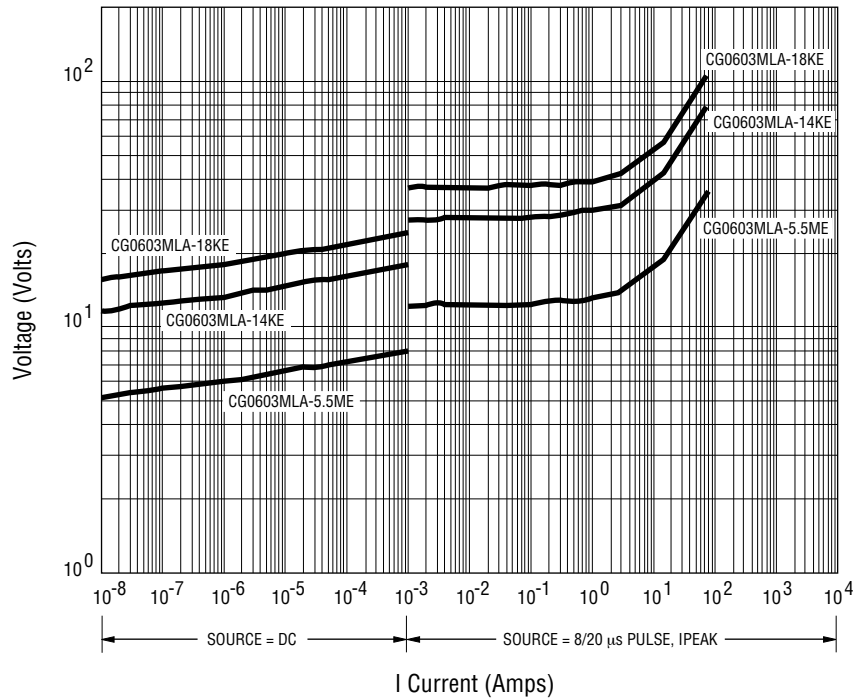
Tape & Reel Packaging
 E = 4,000 pcs. per reel (CG0603MLA Series)
 G = 10,000 pcs. per reel (CG0402MLA Series)

Ni barrier terminations are standard on all ChipGuard® part numbers.

** Only models lower than 10 volts require decimal point.

*RoHS Directive 2002/95/EC Jan. 27, 2003 including annex and RoHS Recast 2011/65/EU June 8, 2011. Specifications are subject to change without notice. Customers should verify actual device performance in their specific applications.

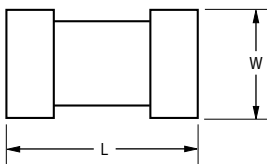
Voltage-Current Characteristics



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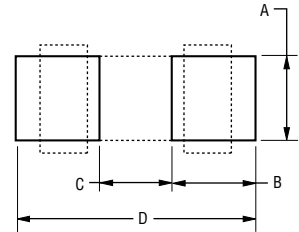
Product Dimensions



DIMENSIONS: $\frac{\text{MM}}{\text{(INCHES)}}$

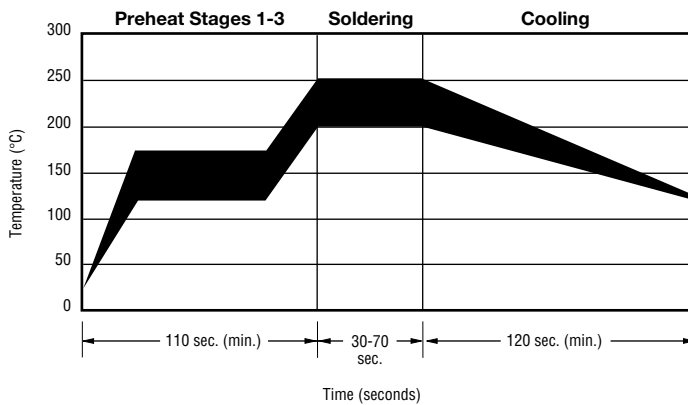
Dimension	CG0402MLA Series	CG0603MLA Series
L	$\frac{1.00 \pm 0.15}{(0.04 \pm 0.006)}$	$\frac{1.60 \pm 0.20}{(0.064 \pm 0.008)}$
W	$\frac{0.50 \pm 0.10}{(0.02 \pm 0.004)}$	$\frac{0.80 \pm 0.20}{(0.032 \pm 0.008)}$
A	$\frac{0.50 \pm 0.10}{(0.02 \pm 0.004)}$	$\frac{0.80 \pm 0.20}{(0.032 \pm 0.008)}$
B	$\frac{0.25 \pm 0.15}{(0.10 \pm 0.006)}$	$\frac{0.30 \pm 0.20}{(0.012 \pm 0.008)}$

Recommended Pad Layout



Dim.	CG0402MLA Series	CG0603MLA Series
A	$\frac{0.51}{(0.020)}$	$\frac{0.76}{(0.030)}$
B	$\frac{0.61}{(0.024)}$	$\frac{1.02}{(0.040)}$
C	$\frac{0.51}{(0.020)}$	$\frac{0.50}{(0.020)}$
D	$\frac{1.70}{(0.067)}$	$\frac{2.54}{(0.100)}$

Solder Reflow Recommendations



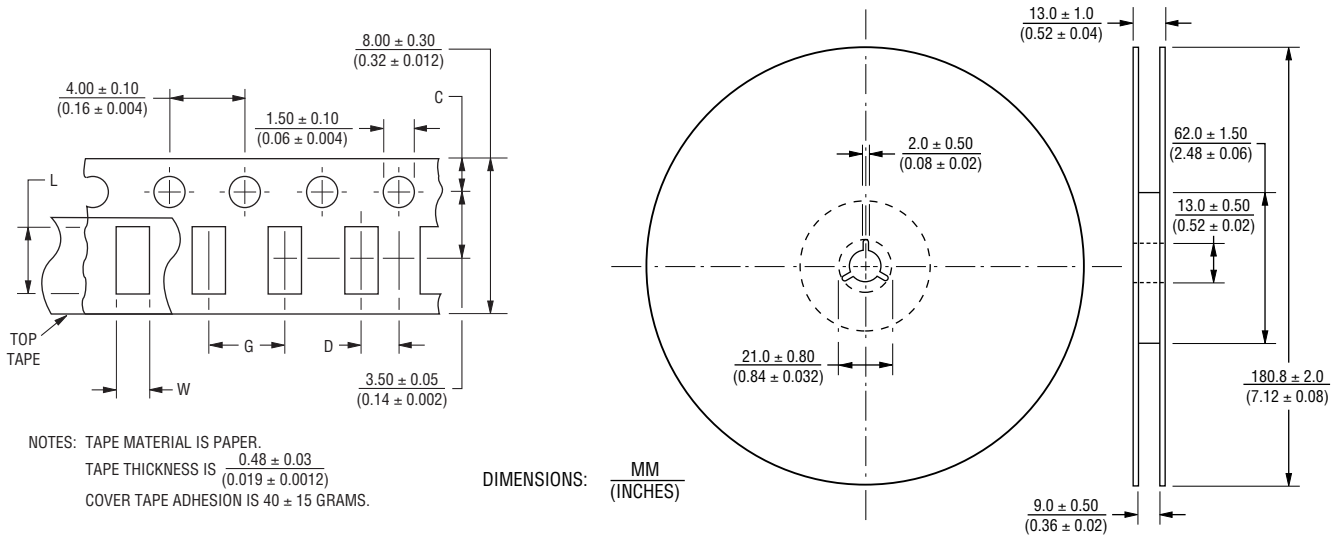
A	Stage 1 Preheat	Ambient to Preheating Temperature	30 s to 60 s
B	Stage 2 Preheat	140 °C to 160 °C	60 s to 120 s
C	Stage 3 Preheat	Preheat to 200 °C	20 s to 40 s
D	Main Heating	200 °C 210 °C 220 °C 230 °C 240 °C	60 s to 70 s 55 s to 65 s 50 s to 60 s 40 s to 50 s 30 s to 40 s
E	Cooling	200 °C to 100 °C	1 °C/s to 4 °C/s

- This product can be damaged by rapid heating, cooling or localized heating.
- Heat shocks should be avoided. Preheating and gradual cooling recommended.
- Excessive solder can damage the device. Print solder thickness of 150 to 200 um recommended.
- Solder gun tip temperature should be kept below 280 °C and should not touch the device directly. Contact should be less than 3 seconds. A solder gun under 30 watts is recommended.

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Packaging Dimensions



Dimension	CG0402MLA Series	CG0603MLA Series
C	$\frac{1.75 \pm 0.05}{(0.04 \pm 0.002)}$	$\frac{1.75 \pm 0.10}{(0.04 \pm 0.004)}$
D	$\frac{2.00 \pm 0.02}{(0.08 \pm 0.0008)}$	$\frac{2.00 \pm 0.05}{(0.08 \pm 0.002)}$
L	$\frac{1.19 \pm 0.05}{(0.047 \pm 0.002)}$	$\frac{1.80 \pm 0.20}{(0.072 \pm 0.008)}$
W	$\frac{0.69 \pm 0.05}{(0.027 \pm 0.002)}$	$\frac{0.90 \pm 0.20}{(0.036 \pm 0.008)}$
G	$\frac{2.0 \pm 0.05}{(0.08 \pm 0.002)}$	$\frac{4.0 \pm 0.05}{(0.16 \pm 0.002)}$